

ANS: D

PTS: 1

REF: Heat Sinks

4. When a component is mounted to a heat sink, _____ is generally used to ensure a good thermal contact between the device and the heat sink.
- a. thermal compound
 - b. insulation compound
 - c. resistance compound
 - d. break compound

ANS: A

PTS: 1

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5. _____ is used to fill in the gaps between the two surfaces and provide good thermal contact.
- a. Insulation compound
 - c. Break compound

b. Thermal compound

d. Lock compound

ANS: B

PTS: 1

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